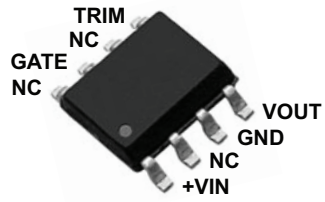
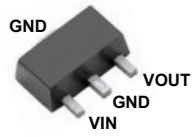


LR645

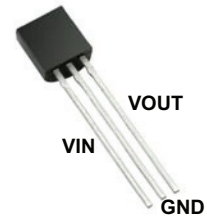
Package Type



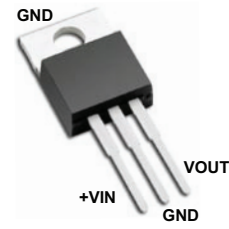
8-Lead SOIC



TO-243AA (SOT-89)



TO-92



TO-220

See [Table 2-1](#) for pin information

1.0 ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

Input Voltage	450V
Output voltage.....	15.5V
Operating and storage temperature.....	-55°C to +150°C

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operational listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

1.1 ELECTRICAL SPECIFICATIONS

TABLE 1-1: ELECTRICAL CHARACTERISTICS ¹

Symbol	Parameter	Min	Typ	Max	Units	Conditions
V _{OUT}	Output voltage	9.3	10	10.7	V	No load
	Output voltage over temperature ²	9.0	10	11.5	V	T _J = - 40 to +125°C, No load
ΔV _{OUT}	Line regulation	-	40	200	mV	V _{IN} = 15 to 400V, No load
	Load regulation	-	150	400	mV	V _{IN} = 50V, I _{OUT} = 0 to 3.0mA
V _{IN}	Operating input voltage range	15	-	450	V	
I _{INQ}	Input quiescent current	-	50	150	μA	No Load
I _{OFF}	V _{IN} off-state leakage current	-	0.1	10	μA	V _{AUX} ≥ V _{OUT} +1V applied to V _{OUT} pin
I _{AUX}	Input current to V _{OUT}	-	-	200	μA	V _{AUX} ≥ V _{OUT} +1V applied to V _{OUT} pin
ΔV _{OUT} /ΔV _{IN}	Ripple rejection ratio ²	50	60	-	dB	120 Hz, No Load
e _n	Noise voltage ²	-	25	-	μV	0.01 to 100 KHz
I _{PEAK}	Output peak current ³	-	30	-	mA	C _{OUT} = 10 μF, V _{IN} = 400V
V _{AUX}	External voltage applied to V _{OUT}	-	-	13.2	V	
8-lead, adjustable voltage version only						
V _{OUT}	Output regulation trim range ²	8	-	12	V	No load
ΔV _{OUT}	Load regulation at 8V trim ²	-	200	400	mV	V _{IN} = 15V, I _{OUT} = 0 to 1.0 mA
	Load regulation at 12V trim ²	-	100	400	mV	V _{IN} = 50V, I _{OUT} = 0 to 3.0 mA

1 Test Conditions unless otherwise specified: T_A = 25°C, V_{IN} = 15V-450V, C_{OUT} = 0.01 μF

2 Guaranteed by design

3 Pulse test duration <1.0 msec, duty cycle <2%

TABLE 1-2: THERMAL CHARACTERISTICS¹

Package	θ _{ja}	Power Dissipation @T _A =25°C
8-lead SOIC	101°C/W	0.31
TO-92	132°C/W	0.74
TO-220	29°C/W	1.8
TO-243AA (SOT-89)	133°C/W	1.6

1 Mounted on FR5 board; 25mm x 25mm x 1.57mm. Significant P_D increase possible on ceramic substrate.

LR645

2.0 PIN DESCRIPTION

The locations of the pins are listed in [Package Type](#).

TABLE 2-1: PIN DESCRIPTION

Function	Description
VIN	Regulator input. 8 - 450V.
GND	Ground return for all internal circuitry. This pin must be electrically connected to circuit common.
GATE	Output GATE driver for an external N-channel depletion.
TRIM	A voltage divider from V_{OUT} to this pin adjusts the output voltage.
VOUT	Regulator output.
NC	No connection.

3.0 FUNCTIONAL DESCRIPTION

3.1 SMPS Start-Up Circuit

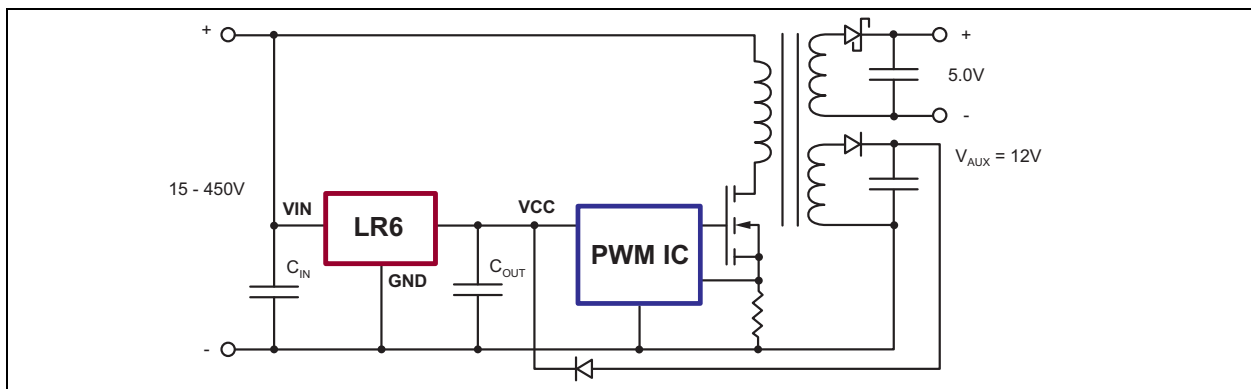
One of the main applications for LR645 is a start-up circuit for off-line, switch-mode power supplies (SMPS), as shown in Figure 3-1. A minimum output capacitance of 10 nF is recommended for stability. The wide operating, input voltage range of LR645 allows the SMPS to operate and start-up from rectified AC, or a DC voltage of 15 to 450V, without adjustment.

During start-up, the LR645 powers the V_{CC} line of the Pulse-Width Modulation (PWM) IC with a nominal output voltage of 10V. The auxiliary voltage connected

through a diode to the V_{OUT} pin of LR645 will start to increase. When the auxiliary voltage becomes larger than the output voltage LR645 turns OFF both its internal high voltage input line and output voltage, allowing the auxiliary voltage to power the V_{CC} line of the PWM IC. After startup, LR645 doesn't draw any input current from the high-voltage line other than the leakage current of the internal MOSFET switch, which is typically 0.1µA.

The 3-terminal version shown in Figure 3-1 has load regulation guaranteed from 0 to 3.0mA at a fixed nominal output voltage of 10V. Applications requiring higher output current and/or a different output voltage can use the 8 pin adjustable version.

FIGURE 3-1: SMPS START-UP CIRCUIT



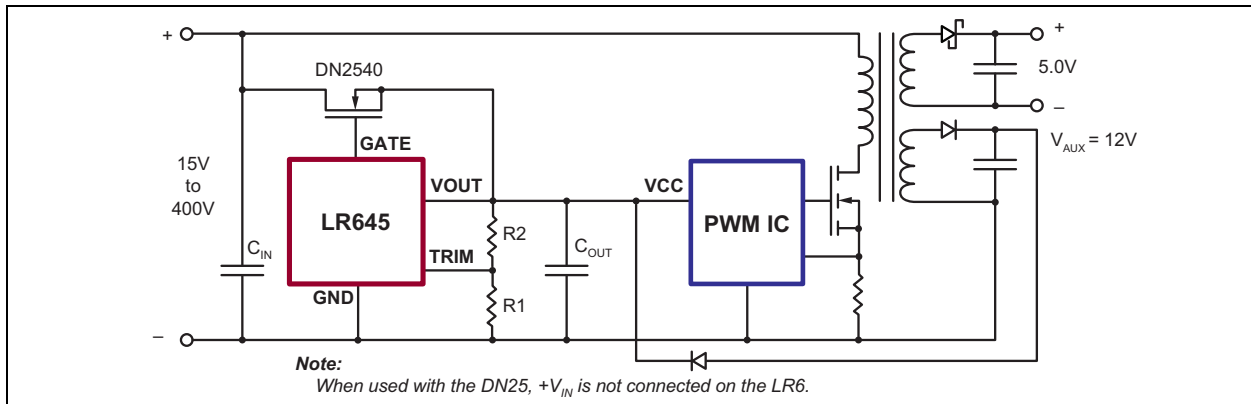
3.2 High-Current SMPS Start-Up Circuit

The 8-lead version of LR645 has connections for an external depletion-mode MOSFET for higher-output current and external resistors for adjustable-output voltage. As shown in Figure 3-2, the output current is increased to 150mA by using the DN2540, a 400V depletion-mode MOSFET. The maximum operating input voltage will be limited by the drain-to-source,

breakdown voltage of the external MOSFET, but cannot exceed the 450V rating of LR645.

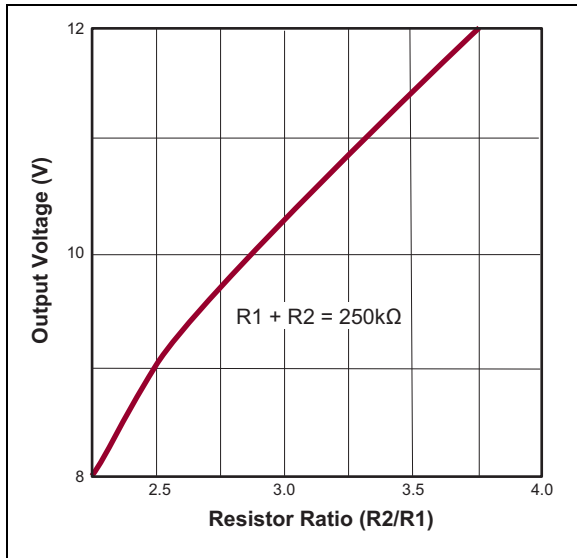
The output voltage can be adjusted from 8 to 12V with two external resistors: R1 and R2. The ratio of R2/R1 determines the output voltage. R2 is connected between the V_{OUT} and TRIM pins; R1 is connected between TRIM and GND pins. Figure 3-3 is a curve showing output voltage versus resistor ratio R2/R1. The optimum range for R1 + R2 is 200KΩ to 300KΩ. This minimizes loading and optimizes accuracy of the output voltage. Figure 3-3 uses an R1 + R2 of 250KΩ.

FIGURE 3-2: HIGH-CURRENT SMPS START-UP CIRCUIT



LR645

FIGURE 3-3: TYPICAL OUTPUT VOLTAGE VS RESISTOR RATIO



3.3 Off Line Linear Regulator

Circuits that require low voltages to operate logic and analog circuits benefit from LR645. The conventional use of step-down transformers can be eliminated, thereby saving space and cost. Some examples of low-voltage applications are: proximity controlled light switches, street lamp controls, and low-voltage power supplies for appliances such as washing machines, dishwashers, and refrigerators.

The wide operating-input voltage range of 15 to 450V, as well as the ripple rejection ratio of 50dB minimum, allows the use of a small, high-voltage input capacitor. The input AC line can be either full-wave or half-wave rectified. A minimum output capacitance of 0.01μF is recommended for output stability.

FIGURE 3-5: HIGH-CURRENT REGULATION

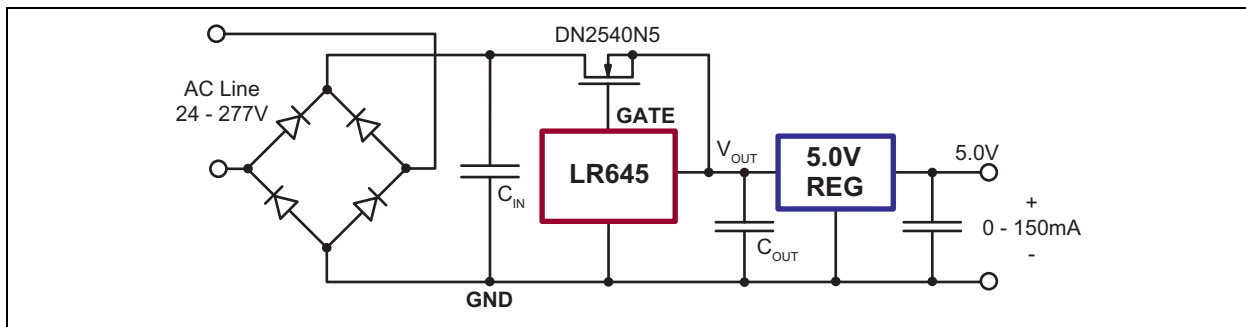
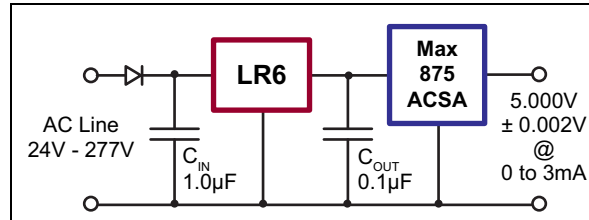


Figure 3-4 shows the LR645 as a pre-regulator to a precision regulator for high precision regulation. Higher output current is also possible by using an external depletion-mode MOSFET DN2540N5 as shown in Figure 3-5.

FIGURE 3-4: CASCADING FOR PRECISION



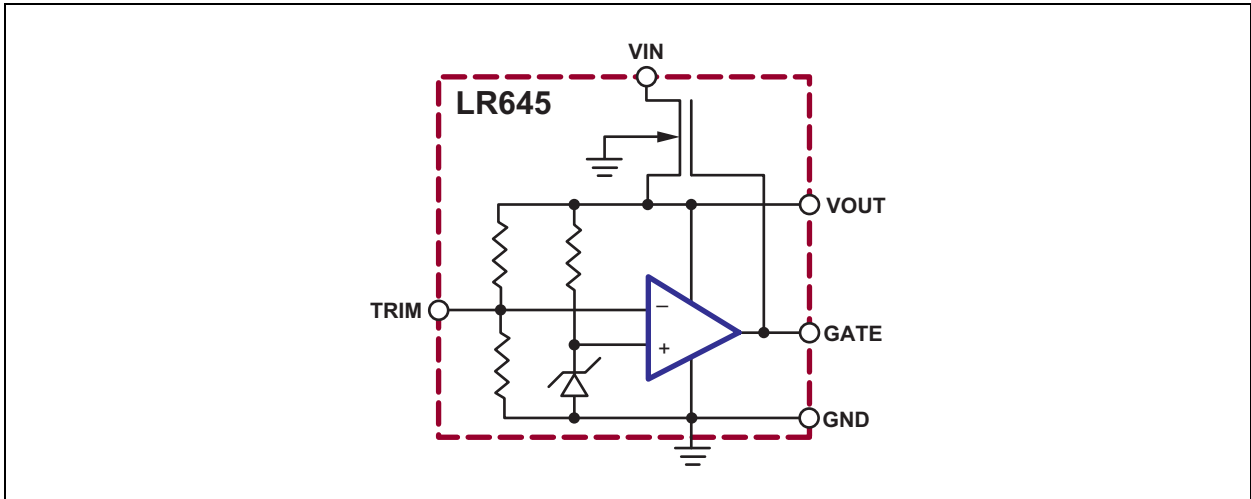
3.4 Power Dissipation Considerations

LR645 is a true linear regulator. Its power dissipation is therefore a function of input voltage and output load current. For example, if the LR645 provides a continuous load current of 3mA at 10V, while its input voltage is 400V, total dissipation in the LR645 will be:

$$\begin{aligned}
 P_{DISS} &= (V_{IN} - V_{OUT}) \times (I_{OUT} + I_{MAXQuiescent}) \\
 &= (400V - 10V) \times (3.0mA + 150\mu A) \\
 &= 1.23Watts
 \end{aligned}$$

The 1.23 watts is for continuous operation. This is within the dissipation capabilities of the TO-220 and SOT-89 packages. See Table 1-2 on Page 3 for deratings. For SMPS start-up applications, the output current is usually required only during start-up. This duration depends upon the auxiliary supply output capacitor and C_{OUT}, but is typically a few hundred milliseconds. All package types of the LR645 have been characterized for use with a C_{OUT} of at least 10μF, and an AC line of 277V.

FIGURE 3-6: BLOCK DIAGRAM

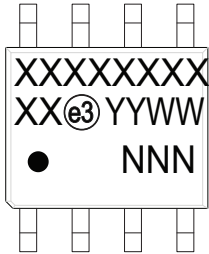


LR645

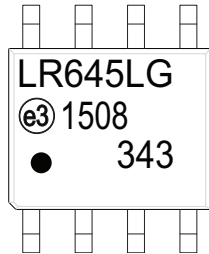
4.0 PACKAGING INFORMATION

4.1 Package Marking Information

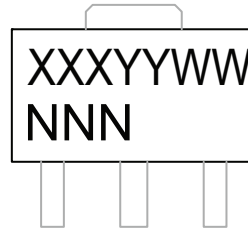
8-lead SOIC



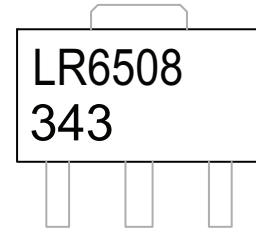
Example



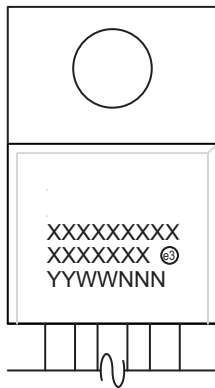
3-lead TO-243AA *
(SOT-89)



Example



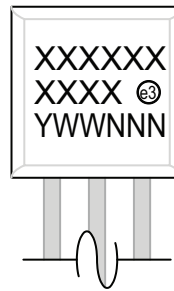
3-lead TO-220



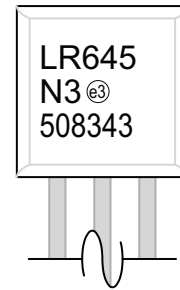
Example



3-lead TO-92



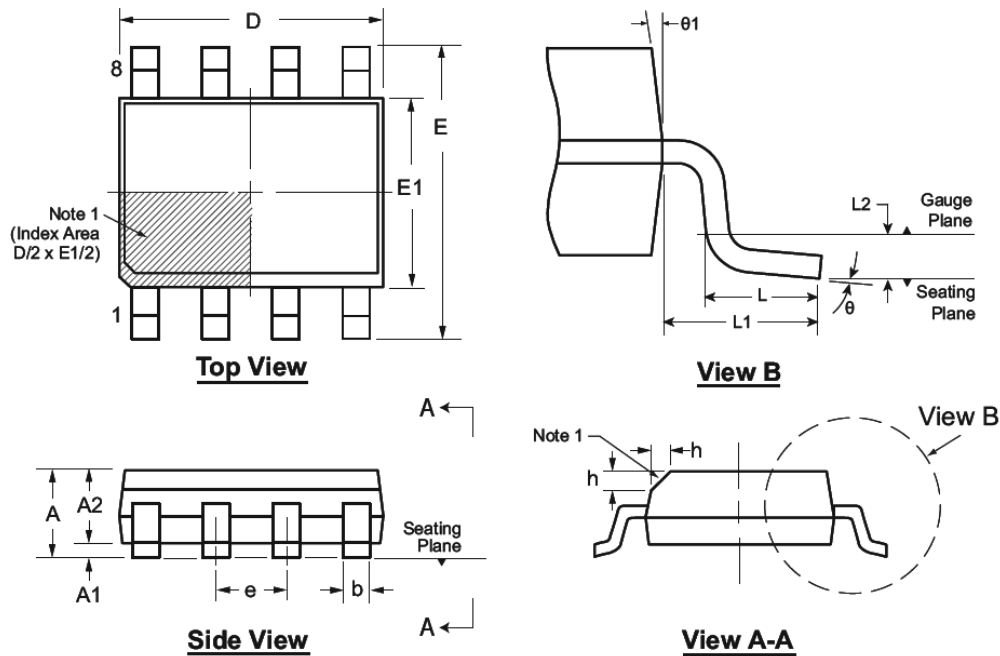
Example



Legend: XX...X Product Code or Customer-specific information
 Y Year code (last digit of calendar year)
 YY Year code (last 2 digits of calendar year)
 WW Week code (week of January 1 is week '01')
 NNN Alphanumeric traceability code
 (e3) Pb-free JEDEC® designator for Matte Tin (Sn)
 * This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

8-Lead SOIC (Narrow Body) Package Outline (LG/TG) 4.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Note:

1. This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

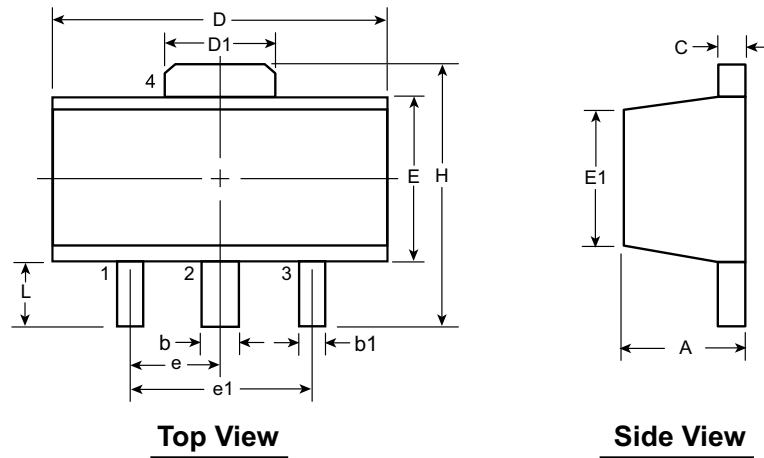
Symbol	A	A1	A2	b	D	E	E1	e	h	L	L1	L2	θ	θ_1	
Dimension (mm)	MIN	1.35*	0.10	1.25	0.31	4.80*	5.80*	3.80*	1.27 BSC	0.25	0.40	1.04 REF	0.25 BSC	0°	5°
	NOM	-	-	-	-	4.90	6.00	3.90		-	-			-	-
	MAX	1.75	0.25	1.65*	0.51	5.00*	6.20*	4.00*		0.50	1.27			8°	15°

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.

* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

3-Lead TO-243AA (SOT-89) Package Outline (N8)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

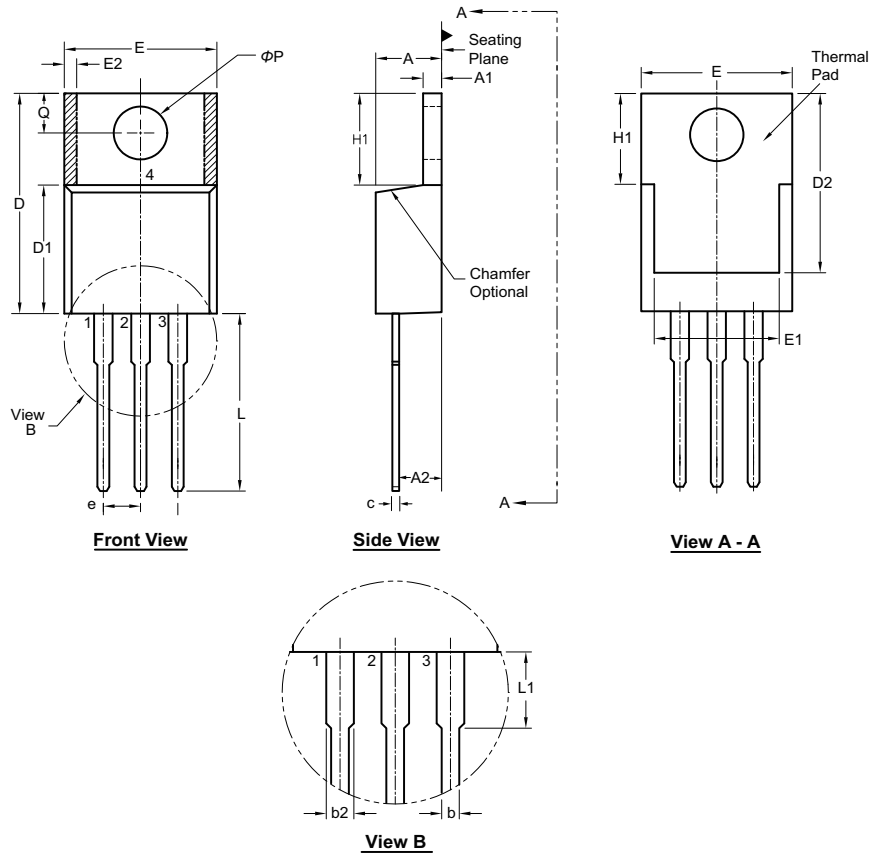
Symbol	A	b	b1	C	D	D1	E	E1	e	e1	H	L		
Dimensions (mm)	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00 [†]	1.50 BSC	3.00 BSC	3.94	0.73 [†]	
	NOM	-	-	-	-	-	-	-	-			-	-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29			4.25	1.20	

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.

[†] This dimension differs from the JEDEC drawing

Drawings not to scale.

3-Lead TO-220 Package Outline (N5)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbol	A	A1	A2	b	b2	c	D	D1	D2	E	E1	E2	e	H1	L	L1	Q	ΦP		
Dimension (inches)	MIN	.140	.020	.080	.015	.045	.012†	.560	.326†	.474†	.380	.270	0.20*	.100 BSC	.230	.500	.200*	.100	.139	
	NOM	-	-	-	.027	.057	-	-	-	-	-	-	-		-	-	-	-	-	-
	MAX	.190	.055	.120†	.040	.070	.024	.650	.361†	.507	.420	.350	.030		.270	.580	.250	.135	.161	

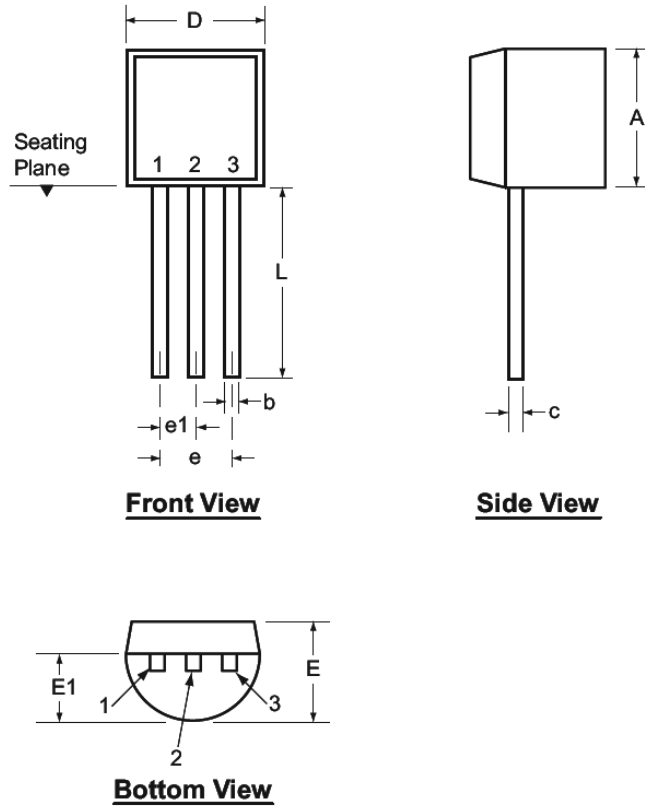
JEDEC Registration TO-220, Variation AB, Issue K, April 2002.

* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

3-Lead TO-92 Package Outline (L/LL/N3)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

APPENDIX A: REVISION HISTORY

Revision A (April 2015)

- Update file to new format

LR645

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>XX</u>	-	<u>X</u>	-	<u>X</u>
Device	Package Options		Environmental		Media Type
Device:	LR645	=	High-Input, Voltage SMPS, Start-up/Linear Regulator		
Package:	LG	=	8-lead SOIC (adjustable voltage)		
	N3	=	TO-92 (fixed voltage)		
	N5	=	TO-220(fixed voltage)		
	N8	=	TO-243AA (SOT-89) (fixed voltage)		
Environmental	G	=	Lead (Pb)-free/ROHS-compliant package		
Media Type:	(blank)	=	3300/Reel for LG packages		
		=	1000/Bag for N3 packages		
		=	50/Tube for TO-220 packages		
		=	2000/Reel for TO-243AA packages		
	P003	=	2000/Reel for N3 package		
	P013	=	2000/Ammo Pack for N3 package		

Examples:		
a)	LR645LG-G:	8-lead SOIC package, 3300/reel.
b)	LR645N3-G	TO-92 package, 1000/bag
c)	LR645N3-G-P003:	TO-92 package, 2000/reel.
d)	LR645N3-G-P013:	TO-92 package, 2000/ammo pack.
e)	LR645N5-G	TO-220 package, 50/tube
f)	LR645N8-G	TO-243AA package, 2000/reel

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rPIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MTP, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.


Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniclient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rLAB, Select Mode, SQI, Serial Quad I/O, Total Endurance, TSHARC, UniWinDriver, WiperLock, ZENA and Z-Scale are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

GestIC and ULPP are registered trademarks of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2015, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

ISBN: 978-1-63277-244-2

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC[®] MCUs and dsPIC[®] DSCs, KEELOQ[®] code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949 ==



MICROCHIP

Worldwide Sales and Service

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://www.microchip.com/support>

Web Address:
www.microchip.com

Atlanta

Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Austin, TX

Tel: 512-257-3370

Boston

Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago

Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland

Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas

Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit

Novi, MI
Tel: 248-848-4000

Houston, TX

Tel: 281-894-5983
Indianapolis

Noblesville, IN

Tel: 317-773-8323
Fax: 317-773-5453

Los Angeles

Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

New York, NY

Tel: 631-435-6000

San Jose, CA

Tel: 408-735-9110

Canada - Toronto

Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon

Hong Kong

Tel: 852-2943-5100
Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8569-7000
Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Dongguan

Tel: 86-769-8702-9880

China - Hangzhou

Tel: 86-571-8792-8115
Fax: 86-571-8792-8116

China - Hong Kong SAR

Tel: 852-2943-5100
Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8864-2200
Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

ASIA/PACIFIC

China - Xiamen

Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040
Fax: 86-756-3210049

India - Bangalore

Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-3019-1500

Japan - Osaka

Tel: 81-6-6152-7160
Fax: 81-6-6152-9310

Japan - Tokyo

Tel: 81-3-6880-3770
Fax: 81-3-6880-3771

Korea - Daegu

Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-5778-366
Fax: 886-3-5770-955

Taiwan - Kaohsiung

Tel: 886-7-213-7828

Taiwan - Taipei

Tel: 886-2-2508-8600
Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Dusseldorf

Tel: 49-2129-3766400

Germany - Munich

Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Germany - Pforzheim

Tel: 49-7231-424750

Italy - Milan

Tel: 39-0331-742611
Fax: 39-0331-466781

Italy - Venice

Tel: 39-049-7625286

Netherlands - Drunen

Tel: 31-416-690399
Fax: 31-416-690340

Poland - Warsaw

Tel: 48-22-3325737

Spain - Madrid

Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

Sweden - Stockholm

Tel: 46-8-5090-4654

UK - Wokingham

Tel: 44-118-921-5800
Fax: 44-118-921-5820

01/27/15